

Silicon Pin Diode

This device is designed primarily for VHF band switching applications but is also suitable for use in general–purpose switching circuits. Supplied in a Surface Mount package.

- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Capacitance − 0.7 pF Typ at V_R = 20 Vdc
- Very Low Series Resistance at 100 MHz 0.34 Ohms (Typ) @ $I_F = 10 \text{ mAdc}$
- Device Marking: 4D

MMVL3401T1

SILICON PIN SWITCHING DIODE





ORDERING INFORMATION

Device		Package	Shipping		
MMVL3	401T1	SOD-323	3000 / Tape & Reel		

MAXIMUM RATINGS

Symbol	Rating	Value	Unit	
V_R	Continuous Reverse Voltage	20	Vdc	
I _F	Peak Forward Current	20	mAdc	

THERMALCHARACTERISTICS

Symbol	Characteristic	Max	Unit
P₀	Total Device Dissipation FR-5 Board,*	200	mW
	$T_A = 25$ °C		
	Derate above 25°C	1.57	mW/°C
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	635	°C/W
T_J, T_{stg}	Junction and Storage Temperature	150	°C

^{*}FR-4 Minimum Pad

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse BreakdownVoltage	$V_{(BR)R}$	35	_	_	Vdc
$(I_R = 10 \mu Adc)$					
Diode Capacitance	C_{T}	_	_	1.0	pF
$(V_R = 20 \text{ Vdc})$					
Series Resistance	$R_{\rm s}$	_	_	0.7	Ω
(I _F = 10 mAdc, f =100MHz)					
Reverse Leakage Current	I _R	_	_	0.1	μAdc
$(V_R = 25 \text{ Vdc})$					



MMVL3401T1

TYPICAL CHARACTERISTICS

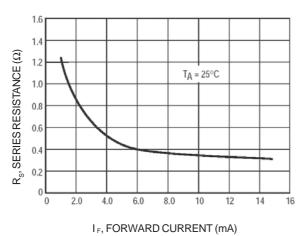


Figure 1. Series Resistance

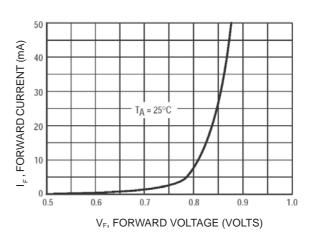


Figure 2. Forward Voltage

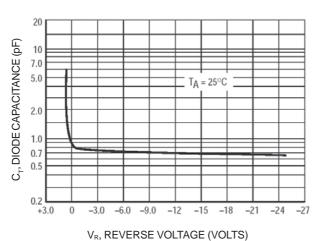
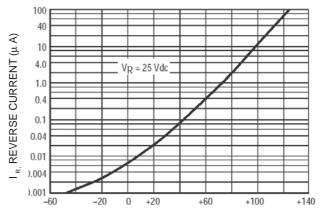


Figure 3. Diode Capacitance



 $\mathsf{T}_{A}, \mathsf{AMBIENTTEMPERATURE} \, (^{\circ}\mathsf{C})$

Figure 4. Leakage Current